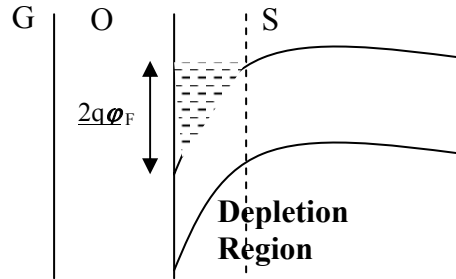


MOS Threshold Voltage

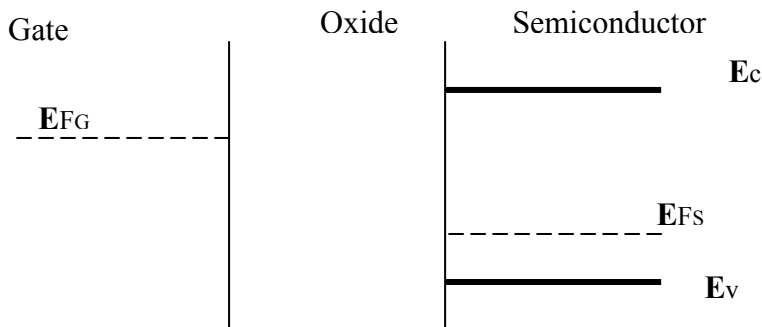
- This is the gate voltage required to strongly invert the surface of the substrate :
 N-Type substrate → we need to Bend the Bands Upward by $2q\phi_F$.
 P-Type substrate → we need to Bend the Bands Downward by $2q\phi_F$.



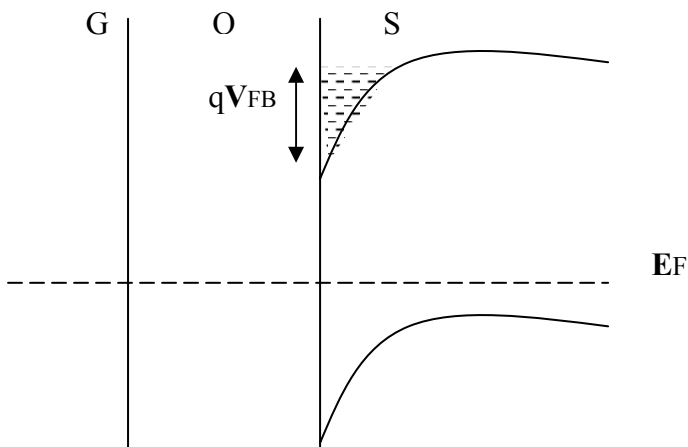
$V_{th} = \text{Flat Band voltage } (V_{FB}) - 2q\phi_F + \text{Voltage to sustain the Depletion region charge } (-Q_B/C_{ox}) + \text{Voltage to overcome the Oxide trapped charge } (-Q_{ox}/C_{ox})$

- Flat Band Voltage V_{FB} : The Voltage required to flatten the energy Bands, at the surface of the substrate $V_{FB} = E_{FG} - E_{FS} = \Phi_G - \Phi_S$

Initially Before Contact:



After



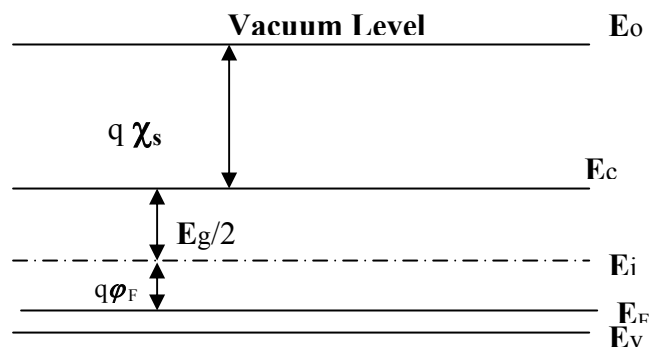
Φ_G = Gate Work function

Φ_S = Substrate Work function (Depends on the Doping)

$$= \chi_s + E_g/2q - \phi_F$$

χ_s : Electron Affinity ($E_o - E_c$)

The Work function is the Energy required to remove an electron from the Fermi level to outside the Solid.



Vacuum Level: Energy level that electrons outside Semiconductor

→ +ve V_{FB} means that Bands are Bent Upward at zero Bias (since We need a +ve voltage to push them down to make them flat).

→ -ve V_{FB} means that Bands are Bent Downward at zero Bias (since We need a -ve voltage to pull them up to make them flat).

$$\phi_F = V_T \ln(N_D/n_i) \quad \text{For N-Type substrate.}$$

$$\phi_F = -V_T \ln(N_A/n_i) \quad \text{For P-Type substrate.}$$

$$\bullet \text{ } Q_B, \text{ the Depletion charge} = + \sqrt{(2q N_{Sub} \epsilon_{Sub} |2\phi_F|)} \quad \text{For N-Type substrate}$$

$$= - \sqrt{(2q N_{Sub} \epsilon_{Sub} |2\phi_F|)} \quad \text{For P-Type substrate}$$

N_{Sub} = net substrate Doping.

ϵ_{Sub} = Dielectric constant of substrate.

e.g) For Si $\epsilon_{Si} = \epsilon_o \epsilon_{Si}$: $\epsilon_o = 8.85 \times 10^{-14}$; $\epsilon_{Si} = 12$

• Q_{ox} = this is a charge trapped in the Oxide during manufacturing.

Example 1: A MOS device is made with an AL Gate ($\Phi_{AL} = 4.15$ eV) and P-Type substrate ($N_A = 10^{16}$ cm $^{-3}$). The Oxide capacitance = 2 fF/ μ m 2 .
 $f = 1 \times 10^{-15}$. Assume $Q_{ox} = 0$.

Calculate V_{th} $\chi_{si} = 4.1$ eV $E_{g_{si}} = 1.1$ eV = $1.1 * q$ J

Sol

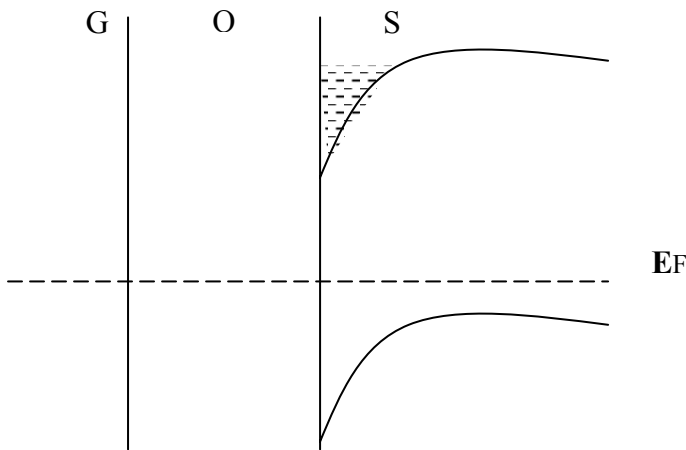
$$V_{th} = V_{FB} - 2\phi_F - Q_B / C_{ox} - Q_{ox} / C_{ox}$$

$$V_{FB} = \Phi_G - \Phi_S = 4.15 - [X_s + E_g/2q - \phi_F] = 4.15 - [4.1 + 0.55 - \phi_F]$$

$$\phi_F = -0.025 \ln(1 \times 10^{16} / 1 \times 10^{10}) = -0.345 \text{ V}$$

$$V_{FB} = 4.15 - 4.1 - 0.55 - 0.345 = -0.89 \text{ V}$$

at zero Bias



$$Q_B = -\sqrt{(2 * 1.6 * 10^{-19} * 10^{16} * 8.85 * 10^{-14} * 12 * 0.69)} = -4.8 * 10^{-8} \text{ C/cm}^2$$

$$C_{ox} = 2 \text{ fF}/\mu\text{m}^2 = 2 * 1 * 10^{-15} * 1 * 10^8 = 2 * 10^{-7} \text{ F/cm}^2$$

$$V_{th} = -0.89 + 0.69 + [4.8 * 10^{-8} / 2 * 10^{-7}] = 0.04 \text{ V}$$

at $V_G = V_{th}$

